



Product/Process Change Notice - PCN 13_0095 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: AD976 and AD976A Polyimide Thickness and Bond Pad Size Change
Publication Date: 13-Sep-2013
Effectivity Date: 12-Dec-2013 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Part 5962-9756401QXA will receive only the bond pad change, but not the polyimide change as previously reported in Rev - of PCN.

Description Of Change

The current polyimide thickness for the AD976 and AD976A is being increased from 7um to 20um.

This applies to all parts in the material list except for part 5962-9756401QXA, which will remain without a polyimide layer.

In addition, the bond pads for REF and VIN are increasing in area (50% in the Y direction). There are no other changes to the die layout. Die size remains the same.

Reason For Change

The thicker polyimide provides increased stress relief for the die in plastic packages, leading to a more predictable performance and delivery.

The bond pad areas are being increased to enable the use of Kelvin probes, improving the manufacturability of the part.

Impact of the change (positive or negative) on fit, form, function & reliability

Changes to the devices will not impact form, fit, function, quality or reliability.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

Supporting Documents

Attachment 1: Type: Qualification Report Summary

ADI_PCN_13_0095_Rev_A_AD976_QP 10064.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (44)

AD976 / AD42/337Z-0RL7	AD976 / AD976AN	AD976 / AD976ANZ	AD976 / AD976AR	AD976 / AD976ARRL
AD976 / AD976ARS	AD976 / AD976ARSZ	AD976 / AD976ARSZRL	AD976 / AD976ARZ	AD976 / AD976ARZRL
AD976 / AD976BNZ	AD976 / AD976BR	AD976 / AD976BRRL	AD976 / AD976BRS	AD976 / AD976BRSZ
AD976 / AD976BRSZ-RL7	AD976 / AD976BRZ	AD976 / AD976BRZRL	AD976 / AD976CNZ	AD976 / AD976CR
AD976 / AD976CRSZ	AD976 / AD976CRZ	AD976A / 5962-9756401QXA	AD976A / AD976AACHIPS	AD976A / AD976AAN
AD976A / AD976AANZ	AD976A / AD976AAR	AD976A / AD976AARS	AD976A / AD976AARSZ	AD976A / AD976AARSZRL
AD976A / AD976AARZ	AD976A / AD976AARZ-RL	AD976A / AD976ABN	AD976A / AD976ABNZ	AD976A / AD976ABR
AD976A / AD976ABRS	AD976A / AD976ABRSZ	AD976A / AD976ABRSZRL	AD976A / AD976ABRZ	AD976A / AD976ABRZRL
AD976A / AD976ACNZ	AD976A / AD976ACR	AD976A / AD976ACRSZ	AD976A / AD976ACRZ	

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	26-Jul-2013	24-Oct-2013	Initial Release
Rev. A	13-Sep-2013	12-Dec-2013	Part 5962-9756401QXA will receive only the bond pad change, but not the polyimide change as previously reported in Rev - of PCN.

Analog Devices, Inc.

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